Summary of Technical Capability

Process Capability

Feature (all dim. in mm)	Current Process Capability	
	Standard	Advanced
Max. Aspect Ratio (PTH)	1 -16	16 - 42
Max. Aspect Ratio (PTH)	08:01	16:01
Min. Drill Size (PTH)	0.3	0.2
Min. Board Thickness	0.5	0.2
Max. Board Thickness	1.6 - 2.0	2.4 - 10.0
Min. Core Thickness	0.1	0.075
Min. Prepreg Thickness	0.075	0.05
Min. Copper Foil Thickness	0.5 oz	0.33 oz
Max. Copper Foil Thickness	2 oz	6 oz
Min. Innerlayer Line / Space	0.125/0.125	0.10/0.10
Min. Outerlayer Line & Space	0.125/0.125	0.075/0.10
Min. Pad dia. for tangency (Drill + x)	0.25	0.2
Press Fit Hole Size Tol. (+/-)	0.075	0.05
Drill Registration Tol. (+/-)	0.075	0.05
Image Registration Tol. (+/-)	0.075	0.05
Soldermask Registration Tol. (+/-)	0.075	0.05
Rout / Scoring Tol. (+/-)	0.125	0.1
Impedance Single Ended Tol. (+/-)	10%	5%
Impedance Differential Tol. (+/-)	10%	5%
Warp and Twist	1%	0.70%

High Density Interconnect (HDI)

Feature (all dim. in mm)	Current Process Capability	
	Standard	Advanced
Mechanical drill Blind Via hole size	0.3	0.25
Laser Blind Via hole size	0.15 - 0.20	0.125 - 0.25
Min. Target / Capture Pad diameter	0.3	0.25
Max. Laser Blind Via Depth	0.075	0.125
Max. Laser blind via Aspect Ratio	0.7	1
HDI Type Construction	1-N-1	2-N-2, Staggered
Copper Fill Plating for Stacked Vias	-	Yes

Special Process Offerings

Feature	Current Process Capability	
	Standard	Advanced
Thermal Heat Sink Attach	No	Yes - low flow prepreg
Via In Pad Technology	No	Yes
Thermal Conductive Ink	No	Yes
Carbon Ink	No	Yes
Buried Resistors	No	Yes
Embedded Capacitance	No	Yes